

EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	4	external electrode and thermosetting conductive paste and resin	US-PGPUB; USPAT	ADJ	ON	2007/11/14 13:59
S2	184	conductive particle and melting point and metal powder and resin and conductive and thermosetting	US-PGPUB; USPAT	ADJ	ON	2007/11/14 14:00
S3	137	conductive particle and melting point and metal powder and resin and conductive and thermosetting and degree	US-PGPUB; USPAT	ADJ	ON	2007/11/14 14:01
S4	38	conductive particle and melting point and metal powder and resin and conductive and thermosetting and degree and (weight or mass) near5 percent	US-PGPUB; USPAT	ADJ	ON	2007/11/14 14:04
S5	15	conductive particle and melting point and metal powder and resin and conductive and thermosetting and degree and (weight or mass) near5 percent and (electrode or plate)	US-PGPUB; USPAT	ADJ	ON	2007/11/14 14:06
S6	15	conductive particle and melting point and metal powder and resin and thermosetting and degree and (weight or mass) near5 percent and (electrode or plate)	US-PGPUB; USPAT	ADJ	ON	2007/11/14 14:07
S7	749	conductive (paste or adhesive) and conductive (powder or particle) and degree and resin and thermoset\$6	US-PGPUB; USPAT	ADJ	ON	2007/11/15 13:04

S8	583	conductive (paste or adhesive) and conductive (powder or particle) and degree and resin and thermoset\$6 and (weight or mass)	US-PGPUB; USPAT	ADJ	ON	2007/11/15 13:08
S9	198	conductive (paste or adhesive) and conductive (powder or particle) and degree and resin and thermoset\$6 and (weight or mass) and melting (point or temperature)	US-PGPUB; USPAT	ADJ	ON	2007/11/15 13:08
S10	136	conductive (paste or adhesive) and conductive (powder or particle) and degree and resin and thermoset\$6 and (weight or mass) and melting (point or temperature) and electrode	US-PGPUB; USPAT	ADJ	ON	2007/11/15 14:03
S11	624	361/306.3.ccls.	US-PGPUB; USPAT	ADJ	ON	2007/11/15 14:04
S12	137	S11 and conductive (paste or adhesive)	US-PGPUB; USPAT	ADJ	ON	2007/11/15 14:47
S13	0	H10-172346	JPO; DERWENT	ADJ	ON	2007/11/15 14:49
S14	14	"172346"	JPO; DERWENT	ADJ	ON	2007/11/15 14:49
S15	0	terminal electrode for electronic component	JPO; DERWENT	ADJ	ON	2007/11/15 14:50
S16	624	361/306.3.ccls.	US-PGPUB; USPAT	ADJ	ON	2007/11/16 08:56
S17	137	S16 and conductive (paste or adhesive) and (tin or sn or indium or in)	US-PGPUB; USPAT	ADJ	ON	2007/11/16 08:56
S18	60	S16 and conductive (paste or adhesive) and (tin or sn or indium)	US-PGPUB; USPAT	ADJ	ON	2007/11/16 08:56
S19	15	("4016463" "4759965" "5375035" "5568352" "5793600" "6002575" "6060150" "6292352" "6300686").PN. OR ("6525921").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2007/11/16 09:15

S20	198	conductive (paste or adhesive) and conductive (powder or particle) and degree and resin and thermoset\$6 and melting (point or temperature) and (weight or mass)	US-PGPUB; USPAT	ADJ	ON	2007/11/16 09:19
S21	29	conductive (paste or adhesive).ti. and conductive (powder or particle) and degree and resin and thermoset\$6 and melting (point or temperature) and (weight or mass)	US-PGPUB; USPAT	ADJ	ON	2007/11/16 09:22
S22	101	("2993815" "3256109" "3410714" "3502609" "3679439" "3681135" "3714709" "3791027" "3800020" "3801364" "3808046" "3857798" "3904555" "3960777" "3983075" "4000016" "4001146" "4127699" "4147669" "4186036" "4233103" "4273593" "4278702" "4293451" "4327124" "4352899" "4353816" "4368281" "4396666" "4400214" "4415486" "4429657" "4434084" "4457861" "4459166" "4496475" "4533685" "4557857" "4564563" "4575432" "4578425" "4581158" "4592861" "4639396" "4652398" "4673532" "4678602" "4680141" "4683653" "4696764" "4705647" "4731130" "4732702" "4733018" "4740252" "4756756" "4765929" "4775500" "4780371" "4786437" "4789411" "4803543" "4808434" "4816184" "4820446" "4830779" "4836955" "4859268" "4872928" "4874548" "4880570" "4882227" "4888135" "4894184" "4940498" "4971727" "4996005" "5088189" "5136365" "5376403")	US-PGPUB; USPAT; USOCR	ADJ	ON	2007/11/16 09:47

		"5463190").PN. OR ("5853622").URPN.				
S23	90	S22 and (weight or mass)	US-PGPUB; USPAT; USOCR	ADJ	ON	2007/11/16 09:53
S24	101	("2993815" "3256109" "3410714" "3502609" "3679439" "3681135" "3714709" "3791027" "3800020" "3801364" "3808046" "3857798" "3904555" "3960777" "3983075" "4000016" "4001146" "4127699" "4147669" "4186036" "4233103" "4273593" "4278702" "4293451" "4327124" "4352899" "4353816" "4368281" "4396666" "4400214" "4415486" "4429657" "4434084" "4457861" "4459166" "4496475" "4533685" "4557857" "4564563" "4575432" "4578425" "4581158" "4592861" "4639396" "4652398" "4673532" "4678602" "4680141" "4683653" "4696764" "4705647" "4731130" "4732702" "4733018" "4740252" "4756756" "4765929" "4775500" "4780371" "4786437" "4789411" "4803543" "4808434" "4816184" "4820446" "4830779" "4836955" "4859268" "4872928" "4874548" "4880570" "4882227" "4888135" "4894184" "4940498" "4971727" "4996005" "5088189" "5136365" "5376403" "5463190").PN. OR ("5853622").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2007/11/19 06:38
S27	3007	layer and capacitor and external electrode	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/03 16:41
S28	313	S27 and thermosetting	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/03 16:42
S29	60	S28 and conductive particles	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/03 16:42

S30	202	conductive (paste or adhesive) and conductive (powder or particle) and degree and resin and thermoset\$6 and melting (point or temperature) and (weight or mass)	US-PGPUB; USPAT	ADJ	ON	2008/03/03 16:48
S31	4	external electrode and thermosetting conductive paste and resin	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:18
S32	186	conductive particle and melting point and metal powder and resin and conductive and thermosetting	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:18
S33	138	conductive particle and melting point and metal powder and resin and conductive and thermosetting and degree	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:18
S34	38	conductive particle and melting point and metal powder and resin and conductive and thermosetting and degree and (weight or mass) near5 percent	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:18
S35	15	conductive particle and melting point and metal powder and resin and conductive and thermosetting and degree and (weight or mass) near5 percent and (electrode or plate)	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:18
S36	15	conductive particle and melting point and metal powder and resin and thermosetting and degree and (weight or mass) near5 percent and (electrode or plate)	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:18
S37	773	conductive (paste or adhesive) and conductive (powder or particle) and degree and resin and thermoset\$6	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:18
S38	601	conductive (paste or adhesive) and conductive (powder or particle) and degree and resin and thermoset\$6 and (weight or mass)	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:18

S39	202	conductive (paste or adhesive) and conductive (powder or particle) and degree and resin and thermoset\$6 and (weight or mass) and melting (point or temperature)	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:18
S40	139	conductive (paste or adhesive) and conductive (powder or particle) and degree and resin and thermoset\$6 and (weight or mass) and melting (point or temperature) and electrode	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:18
S41	647	361/306.3.ccls.	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:18
S42	147	S41 and conductive (paste or adhesive)	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:18
S43	0	H10-172346	JPO; DERWENT	ADJ	ON	2008/03/04 06:18
S44	27	"172346"	JPO; DERWENT	ADJ	ON	2008/03/04 06:18
S45	0	terminal electrode for electronic component	JPO; DERWENT	ADJ	ON	2008/03/04 06:18
S46	647	361/306.3.ccls.	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:18
S47	147	S46 and conductive (paste or adhesive) and (tin or sn or indium or in)	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:18
S48	64	S46 and conductive (paste or adhesive) and (tin or sn or indium)	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:18
S49	15	("4016463" "4759965" "5375035" "5568352" "5793600" "6002575" "6060150" "6292352" "6300686").PN. OR ("6525921").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/04 06:18
S50	202	conductive (paste or adhesive) and conductive (powder or particle) and degree and resin and thermoset\$6 and melting (point or temperature) and (weight or mass)	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:18

S51	29	conductive (paste or adhesive).ti. and conductive (powder or particle) and degree and resin and thermoset\$6 and melting (point or temperature) and (weight or mass)	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:18
S52	101	("2993815" "3256109" "3410714" "3502609" "3679439" "3681135" "3714709" "3791027" "3800020" "3801364" "3808046" "3857798" "3904555" "3960777" "3983075" "4000016" "4001146" "4127699" "4147669" "4186036" "4233103" "4273593" "4278702" "4293451" "4327124" "4352899" "4353816" "4368281" "4396666" "4400214" "4415486" "4429657" "4434084" "4457861" "4459166" "4496475" "4533685" "4557857" "4564563" "4575432" "4578425" "4581158" "4592861" "4639396" "4652398" "4673532" "4678602" "4680141" "4683653" "4696764" "4705647" "4731130" "4732702" "4733018" "4740252" "4756756" "4765929" "4775500" "4780371" "4786437" "4789411" "4803543" "4808434" "4816184" "4820446" "4830779" "4836955" "4859268" "4872928" "4874548" "4880570" "4882227" "4888135" "4894184" "4940498" "4971727" "4996005" "5088189" "5136365" "5376403" "5463190").PN. OR ("5853622").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/04 06:18
S53	90	S52 and (weight or mass)	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/04 06:18

S54	101	("2993815" "3410714" "3679439" "3714709" "3800020" "3808046" "3904555" "3983075" "4001146" "4147669" "4233103" "4278702" "4327124" "4353816" "4396666" "4415486" "4434084" "4459166" "4533685" "4564563" "4578425" "4592861" "4652398" "4678602" "4683653" "4705647" "4732702" "4740252" "4765929" "4780371" "4789411" "4808434" "4820446" "4836955" "4872928" "4880570" "4888135" "4940498" "4996005" "5136365" "5463190").PN. OR ("5853622").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/04 06:18
S55	3010	layer and capacitor and external electrode	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/04 06:18
S56	314	S55 and thermosetting	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/04 06:18
S57	60	S56 and conductive particles	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/03/04 06:18

S58	202	conductive (paste or adhesive) and conductive (powder or particle) and degree and resin and thermoset\$6 and melting (point or temperature) and (weight or mass)	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:18
S59	109	conductive (paste or adhesive) same (tin or sn or indium) and (weight or mass) with (percent or "%") with (tin or sn or indium)	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:33
S60	0	conductive (paste or adhesive) same (tin or sn or indium) and (weight or mass) with (percent or "%") with (tin or sn or indium) and conductive powder and conductive particle	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:40
S61	7	conductive (paste or adhesive) same (tin or sn or indium) and (weight or mass) with (percent or "%") with (tin or sn or indium) and conductive powder	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:41
S62	19	conductive (paste or adhesive) same (tin or sn or indium) and (weight or mass) with (percent or "%") with (tin or sn or indium) and conductive particle	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:41
S63	960	conductive (paste or adhesive) and (weight or mass) with (percent or "%") and conductive particle	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:52
S64	109	conductive (paste or adhesive) and (weight or mass) with (percent or "%") and conductive particle and conductive powder	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:52

S65	22	conductive (paste or adhesive) and (weight or mass) with (percent or "%") and conductive particle and conductive powder and low with melting with (point or temperature)	US-PGPUB; USPAT	ADJ	ON	2008/03/04 06:55
S66	8	conductive (paste or adhesive) same (tin or sn or indium) and (weight or mass) with (percent or "%") with (tin or sn or indium) and conductive powder	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2008/07/08 13:15
S67	913	electrode and (conductive near3 paste) same (tin or sn or indium) and resin	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2008/07/08 13:55
S68	29	electrode and (conductive near3 paste) same (tin or sn or indium) same resin and (tin or sn or indium) same("wt%" or ((weight or mass or wt) near2 (percent or "%")))	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2008/07/08 14:08
S69	136	((TAKESHI) near2 (KIMURA)).INV.	US-PGPUB; USPAT	ADJ	ON	2008/07/08 14:19
S70	2	((YAMATO) near2 (TAKADA)).INV.	US-PGPUB; USPAT	ADJ	ON	2008/07/08 14:19
S71	3	((MICHINORI) near2 (KOMAGATA)).INV.	US-PGPUB; USPAT	ADJ	ON	2008/07/08 14:19
S73	1	((KIMINORI) near2 (YOKOYAMA)).INV.	US-PGPUB; USPAT	ADJ	ON	2008/07/08 14:19
S74	130	electrode and (conductive near3 (paste or adhesive)) same (tin or sn or indium) and (tin or sn or indium) same("wt%" or ((weight or mass or wt) near2 (percent or "%")))	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2008/07/08 14:20
S75	180	((MASAHIRO) near2 (KITAMURA)).INV.	JPO; DERWENT	ADJ	ON	2008/07/08 14:20
S76	11	((MICHINORI) near2 (KOMAGATA)).INV.	JPO; DERWENT	ADJ	ON	2008/07/08 14:21
S77	12	("3947956" "4795670" "5744758" "5879788" "5977490" "6207259" "6440542" "6459046"). PN. OR ("6641898"). URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2008/07/08 14:30

S78	55	(conductive near3 (paste or adhesive)).ab. and (tin or sn or indium) same("wt %" or ((weight or mass or wt) near2 (percent or "%")))) and electrode	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2008/07/08 14:34
S79	105	(conductive near3 (paste or adhesive)).ab. and (tin or sn or indium) same("wt %" or ((weight or mass or wt) near2 (percent or "%"))))	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2008/07/08 14:45
S80	1	1979-24588B.NRAN.	DERWENT	ADJ	ON	2008/07/09 08:24
S81	1	"54022596"	JPO	ADJ	ON	2008/07/09 08:25
S82	1	("5128827").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/02/09 13:20
S83	11	"10279903" OR "10022170"	JPO; DERWENT	ADJ	ON	2009/02/10 12:55
S85	104	(conductive near3 (paste or adhesive)).ab. and (tin or sn or indium) same ("wt %" or ((weight or mass or wt) near2 (percent or "%")))) and (electrode or electronic or electrical)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/05/31 19:25
S86	36	(conductive near3 (paste or adhesive)).ab. and (tin or sn or indium) same ("wt %" or ((weight or mass or wt) near2 (percent or "%")))) and (electrode or electronic or electrical) and thermoset\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/05/31 19:25
S87	352	(conductive near3 (paste or adhesive)) and (tin or sn or indium) same ("wt %" or ((weight or mass or wt) near2 (percent or "%")))) and (electrode or electronic or electrical) and thermoset\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/06/01 06:59
S88	306	(conductive near3 (paste or adhesive)) and (tin or sn or indium) same ("wt %" or ((weight or mass or wt) near2 (percent or "%")))) and (electrode or electronic or electrical) and thermoset\$5 and (powder or particle)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/06/01 07:01

S89	162	(conductive near3 (paste or adhesive)) and (tin or sn or indium) same ("wt %" or ((weight or mass or wt) near2 (percent or "%")))) and (electrode or electronic or electrical) and thermoset\$5 and (powder or particle) with (tin or sn or indium)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/06/01 07:05
S90	766	(conductive near3 (paste or adhesive)) and ((Francium or Fr or Caesium or Cs or Gallium or Ga or Rubidium or Rb or Potassium or K or Sodium or Na or Li or lithium or tin or sn or indium or bi or bismuth)) same ("wt%" or ((weight or mass or wt) near2 (percent or "%")))) and (electrode or electronic or electrical) and thermoset \$5 and (powder or particle) with (Francium or Fr or Caesium or Cs or Gallium or Ga or Rubidium or Rb or Potassium or K or Sodium or Na or Li or lithium or tin or sn or indium or bi or bismuth)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/06/01 07:15
S91	119	(conductive near3 (paste or adhesive)).ab,ti. and ((Francium or Fr or Caesium or Cs or Gallium or Ga or Rubidium or Rb or Potassium or K or Sodium or Na or Li or lithium or tin or sn or indium or bi or bismuth)) same ("wt%" or ((weight or mass or wt) near2 (percent or "%")))) and (electrode or electronic or electrical) and thermoset \$5 and (powder or particle) with (Francium or Fr or Caesium or Cs or Gallium or Ga or Rubidium or Rb or Potassium or K or Sodium or Na or Li or lithium or tin or sn or indium or bi or bismuth)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/06/01 07:15

S92	10	("4221925" "4303715" "5227588" "5473120" "5744758" "5977490" "6087597" "6329610"). PN. OR ("6713687"). URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/06/01 07:31
S93	132	(conductive near3 (paste or adhesive)) with (electrode or electronic or electrical) and ((Francium or Fr or Caesium or Gallium or Rubidium or Rb or Potassium or Sodium or Na or li or lithium or tin or sn or indium or bi or bismuth)) same ("wt%" or ((weight or mass or wt) near2 (percent or "%"))) and thermoset\$5 and (powder or particle) with (Francium or Fr or Caesium or Gallium or Rubidium or Rb or Potassium or Sodium or Na or li or lithium or tin or sn or indium or bi or bismuth)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/06/01 07:35
S94	121	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4) with capacitor.ab,ti. and (terminal or external) same (thermoset\$4 or epoxy) and conductive near2 (adhesive or paste)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/06/01 09:01
S95	921	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (terminal or external) same (thermoset \$4 or epoxy) and conductive near2 (adhesive or paste)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/06/01 09:14
S96	290	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (terminal or external) same (thermoset \$4 or epoxy) same conductive near2 (adhesive or paste)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/06/01 09:17

S98	451	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (terminal or external) same conductive near2 (adhesive or paste) and conductive near2 (adhesive or paste) same (thermoset\$4 or epoxy)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/06/01 09:24
S101	268	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (terminal or external) same conductive near2 (adhesive or paste) and conductive near2 (adhesive or paste) same (thermoset\$4 or epoxy) and (cured or cure or curing)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/06/01 09:30
S102	390	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (terminal or external) same conductive near2 (adhesive or paste) and conductive near2 (adhesive or paste) same (thermoset\$4 or epoxy) and (heat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/06/01 09:34
S103	98	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (terminal or external) same conductive near2 (adhesive or paste) and conductive near2 (adhesive or paste) same (thermoset\$4 or epoxy) and (heat\$4 or cured or curing or cure) and (powder or particle) with (Francium or Fr or Caesium or Cs or Gallium or Ga or Rubidium or Rb or Potassium or K or Sodium or Na or Li or lithium or tin or sn or indium or bi or bismuth)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/06/01 10:17

S104	55	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (terminal or external) same conductive near2 (adhesive or paste) and conductive near2 (adhesive or paste) same (thermoset\$4 or epoxy) and (heat\$4 or cured or curing or cure) and (powder or particle) with (Francium or Fr or Caesium or Gallium or Rubidium or Rb or Potassium or Sodium or li or lithium or tin or sn or indium or bi or bismuth)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/06/01 10:19
S110	457	(powder or particle) same (Francium or Fr or Caesium or Gallium or Rubidium or Rb or Potassium or Sodium or Na or li or lithium or tin or sn or indium or bi or bismuth) same(gold or silver or copper or ag or au or cu) same (thermoset \$4 or epoxy) and first near3 (metal or conductive or powder or particle) and second near3 (metal or conductive or powder or particle)	US-PGPUB; USPAT; USOCR	ADJ	ON	2009/06/01 10:54
S111	242	(powder or particle) same (Francium or Fr or Caesium or Gallium or Rubidium or Rb or Potassium or Sodium or Na or li or lithium or tin or sn or indium or bi or bismuth) same(gold or silver or copper or ag or au or cu) same (thermoset \$4 or epoxy) and first near3 (metal or conductive or powder or particle) and second near3 (metal or conductive or powder or particle) and (electrode or electronic or electrical) and (paste or adhesive) near3 conductive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	ADJ	ON	2009/06/01 10:54

S112	731	(powder or particle) same (Francium or Fr or Caesium or Gallium or Rubidium or Rb or Potassium or Sodium or Na or li or lithium or tin or sn or indium or bi or bismuth) same(gold or silver or copper or ag or au or cu) same (thermoset \$4 or epoxy) and (electrode or electronic or electrical) and (paste or adhesive) near3 conductive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	ADJ	ON	2009/06/01 13:17
S114	242	(powder or particle) same (Francium or Fr or Caesium or Gallium or Rubidium or Rb or Potassium or Sodium or Na or li or lithium or tin or sn or indium or bi or bismuth) same(gold or silver or copper or ag or au or cu) same (thermoset \$4 or epoxy) and first near3 (metal or conductive or powder or particle) and second near3 (metal or conductive or powder or particle) and (electrode or electronic or electrical) and (paste or adhesive) near3 conductive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	ADJ	ON	2009/06/01 13:19
S115	489	S112 not S114	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	ADJ	ON	2009/06/01 13:19
S116	135	S115 and capacitor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	ADJ	ON	2009/06/01 13:19
S117	2	((("5,538,789") or ("5,565,267,"))).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/06/01 13:34
S118	354	S115 not S116	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT	ADJ	ON	2009/06/01 14:11

S119	22	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (terminal or external) same conductive near2 (adhesive or paste) and conductive near2 (adhesive or paste) same (thermoset\$4 or epoxy) and (heat\$4 or cured or curing or cure) and (nickel or Ni) with internal	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/10/08 14:58
S123	25	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (terminal or external) same conductive near2 (adhesive or paste) and conductive near2 (adhesive or paste) same (thermoset\$4 or epoxy) and (nickel or Ni) with internal	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/10/14 15:41
S124	45	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4) and (terminal or external) same conductive near2 (adhesive or paste) and conductive near2 (adhesive or paste) same (thermoset\$4 or epoxy) and (nickel or Ni) with internal	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/10/14 15:48
S125	35	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (terminal or external) same conductive near2 (adhesive or paste) and conductive near2 (adhesive or paste) same (thermoset\$4 or epoxy) and (heat\$4 or cured or curing or cure) and (nickel or Ni) same internal	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/10/14 15:51
S126	13	S125 not S120	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/10/14 15:51

S129	35	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (terminal or external) same conductive near2 (adhesive or paste) and (terminal or external) same (thermoset\$4 or epoxy) and (heat\$4 or cured or curing or cure) and (nickel or Ni) same internal	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/10/29 12:49
S130	18	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (terminal or external) same conductive near2 (adhesive or paste) and (terminal or external) same (thermoset\$4 or epoxy) same (heat\$4 or cured or curing or cure) and (nickel or Ni) same internal	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/10/29 12:51
S131	53	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (terminal or external) same (thermoset \$4 or epoxy) same (heat \$4 or cured or curing or cure) and (nickel or Ni) same internal	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/10/29 13:00
S132	104	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (terminal or external) same (thermoset \$4 or epoxy) and (nickel or Ni) with internal	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/10/29 13:04
S133	407	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (terminal or external) same (heat\$4 or cured or curing or cure) and (nickel or Ni) with internal	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/10/29 13:05

S134	57	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (terminal or external) with (thermoset \$4 or epoxy) and (nickel or Ni) with internal	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/10/29 13:07
S135	70	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and conductive with (thermoset\$4 or epoxy) near3 resin and (nickel or Ni) same internal	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/10/29 13:11
S136	41	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and conductive with (thermoset\$4 or epoxy) near3 resin and (nickel or Ni) with internal	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/10/29 13:11
S137	56	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (terminal or external) same (cured or curing or cure) and (nickel or Ni) with internal	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/10/29 13:38
S138	15	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (terminal or external) with (cured or curing or cure) and (nickel or Ni) with internal	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/10/29 13:43
S139	32	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (terminal or external) with (cured or curing or cure) and (nickel or Ni) same internal	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/10/29 13:44
S140	351	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (terminal or external) with (cured or curing or cure) and (nickel or Ni)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/10/29 13:49

S141	10	361/321.2.ccls. and (nickel or Ni) with (inner or internal or conductive) and (external or termination or terminal) with (cured or cure or curing or thermoset \$4 or epoxy)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/10/29 13:53
S144	1	361/321.1.ccls. and (nickel or Ni) with (inner or internal or conductive) and (external or termination or terminal) with (cured or cure or curing or thermoset \$4 or epoxy) not 361/321.2.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/10/29 13:56
S145	1	361/312.ccls. and (nickel or Ni) with (inner or internal or conductive) and (external or termination or terminal) with (cured or cure or curing or thermoset \$4 or epoxy)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/10/29 13:57
S146	102	"361".clas. and (nickel or Ni) with (inner or internal or conductive) and (external or termination or terminal) with (cured or cure or curing or thermoset \$4 or epoxy) and ceramic	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/10/29 13:58
S147	93	"361".clas. and (nickel or Ni) with (inner or internal) and (external or termination or terminal) same (cured or cure or curing or thermoset\$4 or epoxy) and ceramic	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/10/29 14:05
S148	59	S147 not S146	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/10/29 14:06
S149	44	"361".clas. and (nickel or Ni) with (inner or internal) and (electrode) with (cured or cure or curing or thermoset\$4 or epoxy) and ceramic	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/10/29 14:08
S150	137	"361".clas. and (nickel or Ni) with (inner or internal) and (external or termination or terminal or outer) with (resin) and ceramic	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/10/29 14:20

S151	44	"361".clas. and (nickel or Ni) with (inner or internal) and (external or termination or terminal or outer) with (resin) and ceramic not sinter\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/10/29 14:21
S153	90	capacitor.ab,ti. and (terminal or external or outer) with (thermoset\$4 or resin) and (nickel or Ni) with internal	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/10/29 14:25
S154	7	capacitor.ab,ti. and (terminal or external or outer) with (thermoset\$4) and (nickel or Ni) with internal	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/10/29 14:28
S156	20	capacitor.ab,ti. and (terminal or external or outer) with (thermoset\$4 or resin) and (nickel or Ni) with internal and (cure or cured or curing)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/10/29 14:33
S158	18	capacitor.ab,ti. and (terminal or external or outer) with (thermoset\$4 or resin) and (nickel or Ni) with inner and (cure or cured or curing)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/10/29 14:35
S159	57	capacitor and (terminal or external or outer) with (thermoset\$4 or resin) and (nickel or Ni) with inner and (cure or cured or curing)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/10/29 14:36
S161	244	(terminal or external or outer) with (thermoset\$4 or epoxy) and (nickel or Ni) with inner and (eletronic or electrical)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/02 11:00
S162	22	(terminal or external or outer) with (thermoset\$4 or epoxy) and (nickel or Ni) with inner and piezoelectric	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/02 11:01
S163	2	(terminal or external or outer) with (thermoset\$4 or epoxy) and (nickel or Ni) with inner and ferroelectric	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/02 11:04

S164	120	(terminal or external or outer) with (resin) same2 (cure or cured or curing) and (nickel or Ni) with inner and (eletronic or electrical)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/02 11:08
S165	7	(terminal or external or outer) with (resin) same2 (cure or cured or curing) and (nickel or Ni) with inner and piezoelectric	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/02 11:08
S166	240	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (terminal or external) with (heat\$4 or cured or curing or cure) and (nickel or Ni) with internal	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/02 11:33
S167	132	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (terminal or external) with (heat\$4 or cured or curing or cure) and (nickel or Ni) with internal not ((terminal or external) with (sinter\$4 or firing or fired))	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/02 11:39
S168	8	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (terminal or external) with (cured or curing or cure) and (nickel or Ni) with internal not ((terminal or external) with (sinter\$4 or firing or fired))	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/02 11:39
S169	844	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (terminal or external) and (nickel or Ni) with internal not ((terminal or external) with (sinter\$4 or firing or fired))	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/02 11:40

S170	9	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (terminal or external) with thermoset \$6 and (nickel or Ni) with internal not ((terminal or external) with (sinter\$4 or firing or fired))	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/02 11:40
S171	111	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (terminal or external) with (resin or epoxy) and (nickel or Ni) with internal not ((terminal or external) with (sinter\$4 or firing or fired))	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/02 12:43
S172	42	(US-20060044098-\$ or US-20020079135-\$ or US-20020043652-\$ or US-20010001258-\$ or US-20020100986-\$ or US-20020114726-\$ or US-20020084350-\$).did. or (US-4696764-\$ or US-6525921-\$ or US-5853622-\$ or US-6524721-\$ or US-5376403-\$ or US-3800020-\$ or US-4147669-\$ or US-4233103-\$ or US-4733018-\$ or US-6956731-\$ or US-4398975-\$ or US-4400214-\$ or US-4435611-\$ or US-6713687-\$ or US-7188412-\$ or US-6641898-\$ or US-6936192-\$ or US-5128827-\$ or US-6114413-\$ or US-6370013-\$ or US-5463190-\$ or US-7022266-\$ or US-7075183-\$ or US-5805409-\$ or US-5335139-\$ or US-6621011-\$).did. or (JP-2004059987-\$ or JP-10279903-\$ or JP-10022170-\$ or JP-04096310-\$ or JP-08172227-\$).did. or (JP-54022596-\$ or JP-10022170-\$ or JP-10279903-\$ or WO-9410697-\$).did.	US-PGPUB; USPAT; JPO; DERWENT	ADJ	ON	2009/11/02 12:52
S173	10	S172 and (nickel or ni) with (inner or internal)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/02 12:52

S174	6	S172 and (thermoset\$4) with (external or terminal)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/02 12:56
S175	20	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (terminal or external) with (polymer) and (nickel or Ni) with internal not ((terminal or external) with (sinter\$4 or firing or fired))	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/02 12:59
S176	0	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (terminal or external) with (curable) and (nickel or Ni) with internal not ((terminal or external) with (sinter\$4 or firing or fired))	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/02 13:08
S177	3	electrode and (terminal or external or outer) with (curable) and (nickel or Ni) with internal not ((terminal or external or outer) with (sinter\$4 or firing or fired))	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/02 13:09
S178	13	electrode and (terminal or external or outer) with (cured or curing or cure) with (resin or epoxy or polymer) and (nickel or Ni) with internal not ((terminal or external or outer) with (sinter\$4 or firing or fired))	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/02 13:09
S179	17	electrode and (terminal or external or outer) with (thermoset\$6 or thermo set \$6) and (nickel or Ni) with internal not ((terminal or external or outer) with (sinter\$4 or firing or fired))	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/02 13:11

S180	139	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (terminal or external) with (polymer) and (metal) with internal not ((terminal or external) with (sinter\$4 or firing or fired))	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/09 08:33
S181	8	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (terminal or external) with (polymer) and (metal) with internal not ((terminal or external) with (sinter\$4 or firing or fired)) and capacitor	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/09 08:33
S182	37	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (terminal or external) with (thermoset \$6) and (metal) with internal	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/09 08:34
S183	919	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (terminal or external) with (heat\$5 or cured or cure or curing) and (metal) with internal	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/09 08:42
S184	65	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (terminal or external) with (heat\$5 or cured or cure or curing) with resin and (metal) with internal	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/09 08:42
S185	17	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (terminal or external) with (heat\$5 with (cured or cure or curing)) and (metal) with internal	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/09 08:43
S186	4	piezoelectric and (nickel or Ni) with internal with (advantage or inexpensive or cheap)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/09 08:50

S187	535	piezoelectric and (nickel or Ni) with internal	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/09 08:50
S188	42	piezoelectric actuator and (nickel or Ni) with internal and advantages with (nickel or ni)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/09 08:51
S189	162	piezoelectric actuator and (nickel or Ni) with internal	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/09 08:51
S190	27	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (electrode) with (thermoset\$6) and (nickel or Ni) with (inner or internal)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/09 08:56
S191	61	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (electrode) with (cured or cure or curing or heat\$4) with resin and (nickel or Ni) with (inner or internal)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/09 08:59
S192	289	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (nickel or Ni) with (inner or internal) and thermoset\$5 with resin	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/09 09:03
S193	44	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (external or outer) with (thermoset\$5) with resin and (nickel or Ni) with (inner or internal)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/13 09:00
S194	119	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (external or outer) with (thermoset\$5) and (nickel or Ni) with (inner or internal)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/13 09:24
S195	75	S194 not S193	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/13 09:24
S196	15	S194 not S193 not golf	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/13 09:24

S197	2	"04096310"	JPO; DERWENT	ADJ	ON	2009/11/13 09:31
S198	1	1992-156725.NRAN.	DERWENT	ADJ	ON	2009/11/13 09:31
S199	297	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (external or outer) with (thermoset\$5) and (metal) with (inner or internal)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/13 09:46
S200	146	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (external or outer) with (thermoset\$5) and (metal) with (inner or internal) not golf	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/13 09:48
S201	301	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (external or outer) with (phenol\$5 or \$5phenol or \$5urethane or xylene\$5 or urethane\$5 or \$5xylene) and (metal) with (inner or internal) not golf	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/13 09:52
S202	39	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (external or outer) with (phenol\$5 or \$5phenol or \$5urethane or xylene\$5 or urethane\$5 or \$5xylene) and (ni or nickel) with (inner or internal) not golf	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/13 09:53
S203	5	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (terminal) with (phenol\$5 or \$5phenol or \$5urethane or xylene\$5 or urethane\$5 or \$5xylene) and (ni or nickel) with (inner or internal) not golf	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/13 09:58

S204	32	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (terminal) with (phenol\$5 or \$5phenol or \$5urethane or xylene\$5 or urethane\$5 or \$5xylene) and (metal) with (inner or internal) not golf	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/13 09:59
S205	5	(capacitor).ab,ti. and (terminal or outer or external) with (phenol\$5 or \$5phenol or \$5urethane or xylene\$5 or urethane\$5 or \$5xylene) and (ni or nickel) with (inner or internal)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/13 10:02
S206	12	(capacitor).ab,ti. and (terminal or outer or external) with (phenol\$5 or \$5phenol or \$5urethane or xylene\$5 or urethane\$5 or \$5xylene or thermoset \$6) and (ni or nickel) with (inner or internal)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/13 10:03
S207	483	(capacitor).ab,ti. and (terminal or outer or external) with (paste) and (ni or nickel) with (inner or internal)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/13 10:05
S208	0	(capacitor).ab,ti. and (terminal or outer or external) with (paste) with (set or cured or curing or cure) with resin and (ni or nickel) with (inner or internal)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/13 10:05
S209	9	(capacitor).ab,ti. and (terminal or outer or external) with (paste) with (set or cured or curing or cure) and (ni or nickel) with (inner or internal)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/13 10:05
S210	7	(capacitor).ab,ti. and (terminal or outer or external) with (resin) with (set or cured or curing or cure) and (ni or nickel) with (inner or internal)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/13 10:07

S211	109	(capacitor).ab,ti. and (terminal or outer or external) with (set or cured or curing or cure) and (ni or nickel) with (inner or internal) not baked	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/13 10:07
S212	4	(capacitor).ab,ti. and (terminal or outer or external) with (cured or curing or cure) and (ni or nickel) with (inner or internal) not baked	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/13 10:08
S213	4	(capacitor).ab,ti. and (terminal or outer or external) with (cured or curing or cure) and (ni or nickel) with (inner or internal) not (baked with (terminal or outer or external))	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/13 10:08
S214	3	(capacitor).ab,ti. and (terminal or outer or external) with (cured or curing or cure) and (ni or nickel) with (inner or internal) and resin	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/13 10:09
S215	20	(capacitor).ab,ti. and (terminal or outer or external) with (cured or curing or cure) and (metal) with (inner or internal) and resin	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/13 10:09
S216	0	(capacitor).ab,ti. and (terminal or outer or external) with (thermoset \$5) with (set or cured or curing or cure) and (ni or nickel) with (inner or internal)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/16 10:23
S217	133	(capacitor).ab,ti. and (terminal or outer or external) with (resin) and (ni or nickel) with (inner or internal) and resin	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/16 10:24
S218	3	(capacitor).ab,ti. and (terminal or outer or external) with (polyimide) and (ni or nickel) with (inner or internal) and resin	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/16 10:24

S219	0	(capacitor).ab,ti. and (terminal or outer or external) with (heat\$4 near4 (cured or cure or curing)) and (ni or nickel) with (inner or internal) and resin	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/16 10:25
S220	0	(capacitor).ab,ti. and (terminal or outer or external) with (heat\$4 near4 (cured or cure or curing)) and (ni or nickel) with (inner or internal)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/16 10:25
S221	0	(capacitor).ab,ti. and (terminal or outer or external) with (heat\$4 with (cured or cure or curing)) and (ni or nickel) with (inner or internal)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/16 10:25
S222	155	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4).ab, ti. and (internal or inner) with (ni or nickel) same advantage	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/16 10:41
S223	94	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4) with capacitor.ab,ti. and (internal or inner) with (ni or nickel) same advantage	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/16 10:42
S224	417	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4) with capacitor.ab,ti. and (internal or inner) with (ni or nickel) same (silver or ag or palladium or pd)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/16 10:44
S225	31	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4) with capacitor.ab,ti. and (internal or inner) with (ni or nickel) same (silver or ag or palladium or pd) and (ni or nickel) with advantage	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/16 10:45
S226	4	"2001085263"	JPO; DERWENT	ADJ	ON	2009/11/16 10:50

S227	43	(multilayer\$2 or ceramic or multi near3 layer\$2 or laminat\$4 or stack\$4) with capacitor.ab.ti. and (internal or inner) with (ni or nickel) with advantage	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2009/11/16 10:51
S228	1	"2000348963"	JPO	ADJ	ON	2009/11/16 10:55
S229	315	conduct\$5 near3 (paste or adhesive or glue) and (Ag or silver) and (Sn or tin) and bisphenol\$5 and resol\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2010/02/28 15:43
S230	76	conduct\$5 near3 (paste or adhesive or glue) and (Ag or silver) and (Sn or tin) and bisphenol\$5 same resol\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2010/02/28 15:44
S231	75	conduct\$5 near3 (paste or adhesive or glue) and (Ag or silver) and (Sn or tin) and bisphenol\$5 same resol\$6 and (capacitor or electronic or electrical)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2010/02/28 15:44
S232	22	conduct\$5 near3 (paste or adhesive or glue).ab.ti. and (Ag or silver) and (Sn or tin) and bisphenol\$5 same resol\$6 and (capacitor or electronic or electrical)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2010/02/28 15:49
S233	1	("2005/0230667").URPN.	USPAT	ADJ	ON	2010/02/28 16:10
S234	1	conduct\$5 near3 (paste or adhesive or glue).ab.ti. and (Ag or silver) and (Sn or tin) and bisphenol\$5 same resol\$6 not S232	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2010/02/28 16:11
S235	12	("5716663" "5853622" "5928404" "6663798" "6713687" "6926849").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2010/02/28 16:17
S236	3	S235 and (silver or Ag) and (Tin or Sn) and (phenol or resole) and thermoset\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2010/02/28 16:19

S237	0	conduct\$5 near3 (paste or adhesive or glue) and (Ag or silver) with3 (Sn or tin) same4 (bisphenol\$5 or resol\$6) and (capacitor or electronic or electrical) and bisphenol\$5 same resol\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2010/02/28 16:22
S238	0	conduct\$5 near3 (paste or adhesive or glue) and (Ag or silver) with3 (Sn or tin) same4 (bisphenol\$5 or resol\$6) and bisphenol\$5 same resol\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2010/02/28 16:22
S239	27	conduct\$5 near3 (paste or adhesive or glue) and (Ag or silver) same (Sn or tin) same4 (bisphenol\$5 or resol\$6) and bisphenol\$5 same resol\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2010/02/28 16:22
S246	6	conduct\$5 near3 (paste or adhesive or glue) with (terminal or (external or outer) near4 electrode) and (internal or inner) near4 (conduct\$4 or electrode) with (Ni or nickel) and capacitor.ab.ti. and conduct\$5 near3 (paste or adhesive or glue) with (thermoset\$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2010/03/02 11:19
S247	16	conduct\$5 near3 (paste or adhesive or glue) with (terminal or (external or outer) near4 electrode) and (internal or inner) near4 (conduct\$4 or electrode) with (Ni or nickel) and capacitor and conduct\$5 near3 (paste or adhesive or glue) with (thermoset\$6)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2010/03/02 11:21
S248	26	conduct\$5 near3 (paste or adhesive or glue) with (terminal or (external or outer) near4 electrode) and (internal or inner) near4 (conduct\$4 or electrode) with (Ni or nickel) and capacitor and conduct\$5 near3 (paste or adhesive or glue) with (cured or cure or curing)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2010/03/02 11:22

S249	3	conduct\$5 near3 (paste or adhesive or glue) with (terminal or (external or outer) near4 electrode) and (internal or inner) near4 (conduct\$4 or electrode) with (Ni or nickel) and conduct\$5 near3 (paste or adhesive or glue) with (cured or cure or curing) not S248	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2010/03/02 11:32
S250	1	conduct\$5 near3 (paste or adhesive or glue) with (terminal or (external or outer) near4 electrode) and (internal or inner) near4 (conduct\$4 or electrode) with (Ni or nickel) and conduct\$5 near3 (paste or adhesive or glue) with (thermoset \$5) not S247	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2010/03/02 11:32
S251	54	conduct\$5 near3 (paste or adhesive or glue) with (terminal or (external or outer) near4 electrode) and (internal or inner) near4 (conduct\$4 or electrode) same3 (Ni or nickel) and conduct\$5 near3 (paste or adhesive or glue) with (thermoset\$5 or curing or cured or cure) and (capacitor or electronic).ab,ti.	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2010/03/02 11:34
S252	19	conduct\$5 near3 (paste or adhesive or glue) with (terminal or (external or outer) near4 electrode) and (internal or inner) near4 (conduct\$4 or electrode) same3 (Ni or nickel) and conduct\$5 near3 (paste or adhesive or glue) with (thermoset\$5 or curing or cured or cure) and (capacitor or electronic) not S251	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2010/03/02 11:49
S253	234	361/308.1.ccls. not 361/306.3.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2010/03/02 13:12
S254	39	((MASAHIRO) near2 (KITAMURA)).INV.	US-PGPUB; USPAT	ADJ	ON	2010/03/02 13:12

S255	4057	252/500.ccls. not 361/306.3,308.1.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2010/03/02 13:18
S256	1970	252/500.ccls. not 361/306.3,308.1.ccls. and (capacitor or electronic)	US-PGPUB; USPAT; EPO; JPO; DERWENT	ADJ	ON	2010/03/02 13:18

EAST Search History (I nterference)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S240	0	((multilayer\$3 or multi near3 layer\$4 or stack \$4 or laminat\$6) and thermoset\$6 and conductive near3 (paste or adhesive or glue) and (Ag or silver) and (Tin or Sn) and resol\$6 and bisphenol\$7 and (weight or mass)).clm.	US-PGPUB; USPAT; UPAD	ADJ	ON	2010/03/01 06:44
S241	8	((multilayer\$3 or multi near3 layer\$4 or stack \$4 or laminat\$6) and thermoset\$6 and conductive near3 (paste or adhesive or glue) and (Ag or silver) and (Tin or Sn) and (weight or mass)). clm.	US-PGPUB; USPAT; UPAD	ADJ	ON	2010/03/01 06:44
S242	1	((external or outer) near4 (electrode or terminal) and thermoset\$6 and conductive near3 (paste or adhesive or glue) and (Ag or silver) and (Tin or Sn) and (weight or mass)). clm.	US-PGPUB; USPAT; UPAD	ADJ	ON	2010/03/01 06:48
S243	1	((external or outer) near4 (electrode or terminal) and thermoset\$6 and conductive near3 (paste or adhesive or glue) and (powder) same (particle) and (weight or mass)).clm.	US-PGPUB; USPAT; UPAD	ADJ	ON	2010/03/01 06:49

S244	5	((multilayer\$3 or multi near3 layer\$4 or stack \$4 or laminat\$6) and thermoset\$6 and conductive near3 (paste or adhesive or glue) and (powder) same (particle) and (weight or mass)).clm.	US-PGPUB; USPAT; UPAD	ADJ	ON	2010/03/01 06:49
------	---	---	--------------------------	-----	----	------------------

3/ 2/ 2010 1:43:59 PM

**C:\ Documents and Settings\ dsinclair\ My Documents\ EAST\ Workspaces\ 10\ 53\ 10538136.
wsp**